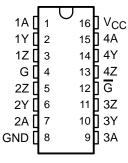
- Meets Standard EIA-485
- Designed for High-Speed Multipoint Transmission on Long Bus Lines in Noisy Environments
- Supports Data Rates up to and Exceeding Ten Million Transfers Per Second
- Common-Mode Output Voltage Range of –7 V to 12 V
- Positive- and Negative-Current Limiting
- Low Power Consumption . . . 1.5 mA Max (Output Disabled)

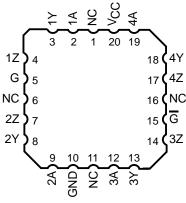
description

The SN55LBC172 is a monolithic quadruple differential line driver with 3-state outputs. This device is designed to meet the requirements of the Electronics Industry Association (EIA) standard RS-485. The SN55LBC172 is optimized for balanced multipoint bus transmission at data rates up to and exceeding 10 million bits per second. The driver features wide positive and negative common-mode output voltage ranges, current limiting, and thermal-shutdown circuitry, making it suitable for party-line applications in noisy environments. The device is designed using the LinBiCMOS™ process, facilitating ultralow power consumption and inherent robustness.

J OR W PACKAGE (TOP VIEW)



FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN55LBC172 provides positive- and negative-current limiting and thermal shutdown for protection from line fault conditions on the transmission bus line. This device offers optimum performance when used with the SN55LBC173M quadruple line receiver.

ORDERING INFORMATION[‡]

TA	PACKAGE [§]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	LCCC – FK	Tube	SNJ55LBC172FK	SNJ55LBC172FK
–55°C to 125°C	CDIP – J	Tube	SNJ55LBC172J	SNJ55LBC172J
	CFP – W	Tube	SNJ55LBC172W	SNJ55LBC172W

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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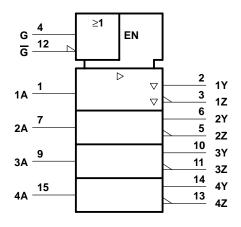
FUNCTION TABLE (each driver)

INPUT	ENA	BLES	OUTPUTS		
Α	G	G G		Z	
Н	Н	Х	Н	L	
L	Н	X	L	Н	
Н	Х	L	Н	L	
L	Х	L	L	Н	
Х	L	Н	Z	Z	

H = high level, L = low level, X = irrelevant,

Z = high impedance (off)

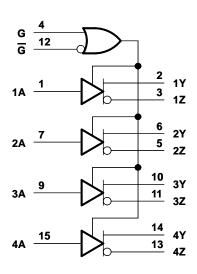
logic symbol†



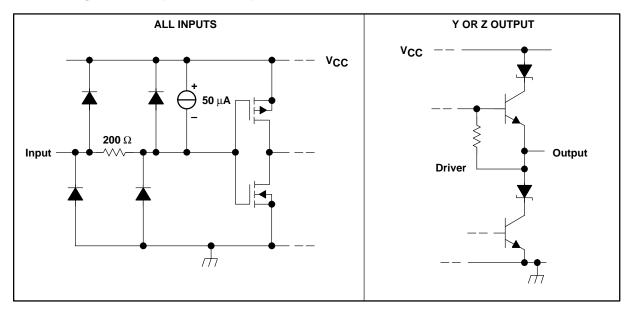
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the J or W package.

logic diagram (positive logic)



schematic diagrams of inputs and outputs



SN55LBC172 QUADRUPLE LOW-POWER DIFFERENTIAL LINE DRIVER

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	0.3 V to 7 V
Output voltage range, VO	–10 V to 15 V
Input voltage range, V _I	0.3 V to 7 V
Continuous power dissipation	
Operating free-air temperature range, T _A	–55°C to 125°C
Storage temperature range, T _{stq}	
Lead temperature 1.6 mm (1/16 inch) from case for	or 10 seconds ——65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A =125°C	T _A = 125°C POWER RATING
FK	1375 mW	11.0 mW/°C	275 mW
J	1375 mW	11.0 mW/°C	275 mW
W	1000 mW	8.0 mW/°C	200 mW

recommended operating conditions

				MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, V _{IH}		2			V
Low-level input voltage, V _{IL}				0.8	V
Output valtage at any bus terminal (constraint or common mode) \/a	Y or Z			12	V
Output voltage at any bus terminal (separately or common mode), VO	1 01 2			-7	ľ
High-level output current, IOH	Y or Z			-60	mA
Low-level output current, I _{OL}	Y or Z			60	mA
Continuous total power dissipation		See	Dissipatio	on Rating	g Table
Operating free-air temperature, T _A	_	-55		125	°C



[‡] The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature. NOTE 1: All voltage values are with respect to GND.

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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST	MIN	TYP [†]	MAX	UNIT	
VIK	Input clamp voltage	$I_{I} = -18 \text{ mA}$				-1.5	V
IV.	Differential cutout valte as †	$R_L = 54 \Omega$,	See Figure 1	1.1	1.8	5	٧
IVODI	Differential output voltage‡	$R_L = 60 \Omega$,	See Figure 2	1.1	1.7	5	V
$\Delta V_{OD} $	Change in magnitude of differential output voltage§					±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega$,	See Figure 1			3 -1	٧
ΔIVOCI	Change in magnitude of common-mode output voltage§]				±0.2	V
IO	Output current with power off	$V_{CC} = 0$, $V_{O} = -7 \text{ V to } 12 \text{ V}$				±100	μΑ
loz	Z High-impedance-state output current Vo		$V_O = -7 V$ to 12 V			±100	μΑ
lн	High-level input current	V _I = 2.4 V				-100	μΑ
IլL	Low-level input current	V _I = 0.4 V				-100	μΑ
los	Short-circuit output current	V _O = -7 V to 12 V				±250	mA
loo	Supply current (all drivers)	No load	Outputs enabled			7	mA
ICC	Supply current (an univers)	INU IUdu	Outputs disabled			1.5	IIIA

 $[\]uparrow$ All typical values are at V_{CC} = 5 V and T_A = 25°C.

switching characteristics, $V_{CC} = 5 \text{ V}$

PARAMETER		TEST CO	NDITIONS	TA	MIN	TYP	MAX	UNIT	
t work	Differential output delay time	$R_1 = 54 \Omega$	See Figure 3	25°C	2	11	20	ns	
td(OD)	Differential output delay time	KL = 54 52,	See Figure 3	−55°C to 125°C	2		40	115	
t. (0.7)	Differential output transition time	$R_1 = 54 \Omega$	$R_1 = 54 \Omega$, See Figure 3		10	15	25	20	
t _t (OD)	OD) Differential output transition time		See Figure 3	−55°C to 125°C	4		60	ns	
t	tp7H Output enable time to high level		See Figure 4	25°C			30	20	
^t PZH	Output enable time to high level	$R_L = 110 \Omega$,	See Figure 4	−55°C to 125°C			40	ns	
t	Output enable time to low level	$R_1 = 110 \Omega$	See Figure 5	25°C			30	ns	
tPZL	Output enable time to low level	KL = 110 22,	See Figure 5	−55°C to 125°C			40	115	
t	Output disable time from high level	$R_1 = 110 \Omega$	See Figure 4	25°C			60	ns	
^t PHZ	Output disable time nom night level	N_ = 110 32, See Figure 4		−55°C to 125°C			115	115	
to. 7	Output disable time from low level	$R_1 = 110 \Omega$	See Figure 5	25°C			30	ns	
^t PLZ	Output disable time nom low level	INL = 110 52,	See i igule 5	-55°C to 125°C			55	115	

[‡] The minimum V_{OD} specification does not fully comply with EIA-485 at operating temperatures below 0°C. The lower output signal should be used to determine the maximum signal transmission distance.

^{§ ∆|}V_{OD}| and ∆|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.

PARAMETER MEASUREMENT INFORMATION

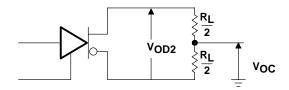


Figure 1. Differential and Common-Mode Output Voltages

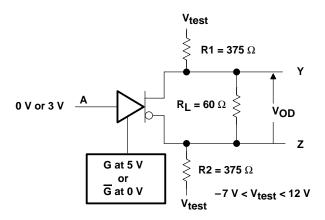
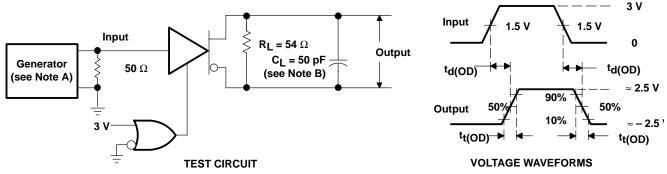


Figure 2. Driver V_{OD} Test Circuit



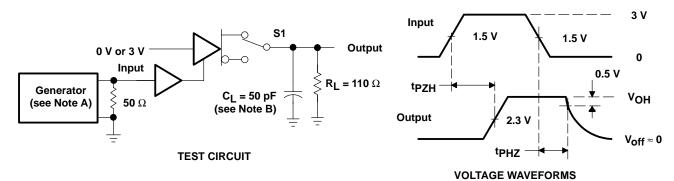
NOTES: A. The input pulses are supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, $t_f \leq$ 5 ns, $t_f \leq$ 5 ns,

B. C_L includes probe and stray capacitance.

Figure 3. Driver Differential-Output Test Circuit and Delay and Transition-Time Waveforms

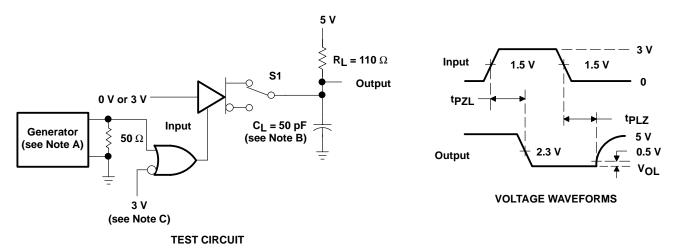


PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, $t_{f} \leq$ 5 ns, $Z_{O} = 50 \ \Omega$.
 - B. C_L includes probe and stray capacitance.

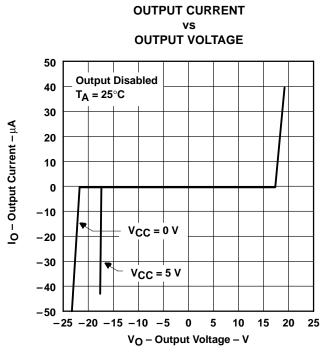
Figure 4. tpzH and tpHZ Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle \leq 50%, $t_f \leq$ 5 ns, $t_f \leq$ 6 ns, $t_f \leq$ 7 ns, $t_f \leq$ 7 ns, $t_f \leq$ 7 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns,
 - B. C_L includes probe and stray capacitance.
 - C. To test the active-low enable \overline{G} , ground G and apply an inverted waveform to \overline{G} .

Figure 5. tpzL and tpLZ Test Circuit and Waveforms

TYPICAL CHARACTERISTICS



LOW-LEVEL OUTPUT CURRENT 5 V_{CC} = 5 V 4.5 T_A = 25°C VOL - Low-Level Output Voltage - V 4 3.5 3 2.5 2 1.5 1 0.5 0 -20 20 40 60 100 120 IOL - Low-Level Output Current - mA

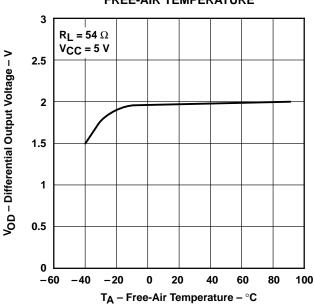
LOW-LEVEL OUTPUT VOLTAGE

Figure 6

Figure 7

HIGH-LEVEL OUTPUT VOLTAGE





VS
HIGH-LEVEL OUTPUT CURRENT

5
VCC = 5

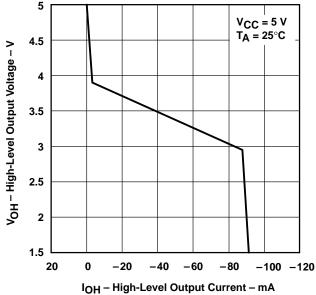


Figure 8

Figure 9



TYPICAL CHARACTERISTICS

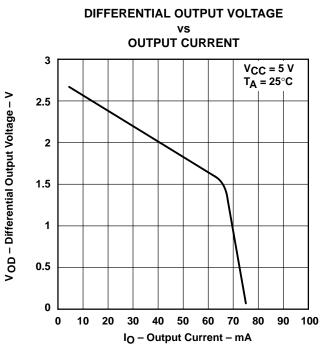


Figure 10

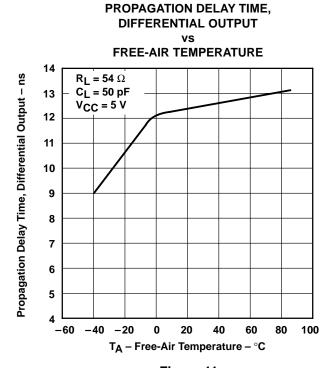


Figure 11

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9076503Q2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9076503Q2A SNJ55 LBC172FK
5962-9076503QEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9076503QE A SNJ55LBC172J
5962-9076503QFA	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9076503QF A SNJ55LBC172W
SNJ55LBC172FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9076503Q2A SNJ55 LBC172FK
SNJ55LBC172FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9076503Q2A SNJ55 LBC172FK
SNJ55LBC172J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9076503QE A SNJ55LBC172J
SNJ55LBC172J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9076503QE A SNJ55LBC172J
SNJ55LBC172W	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9076503QF A SNJ55LBC172W
SNJ55LBC172W.A	Active	Production	CFP (W) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9076503QF A SNJ55LBC172W

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN55LBC172:

Catalog: SN75LBC172

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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TUBE

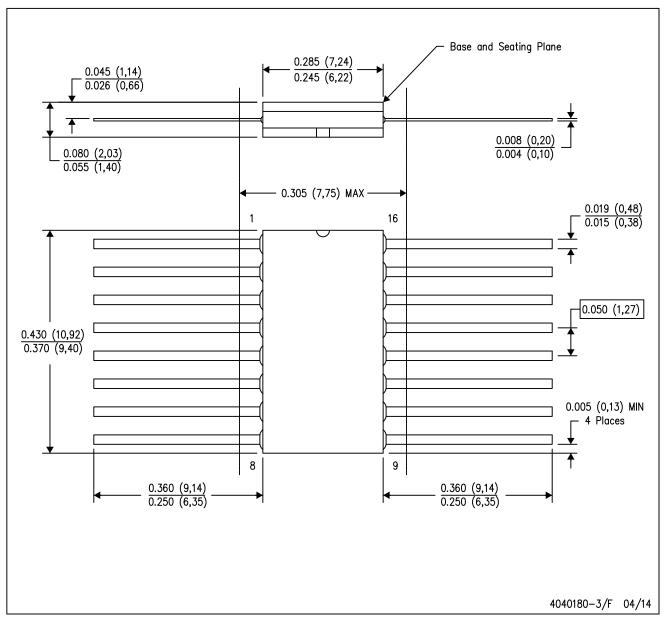


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9076503Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9076503QFA	W	CFP	16	25	506.98	26.16	6220	NA
SNJ55LBC172FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ55LBC172FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ55LBC172W	W	CFP	16	25	506.98	26.16	6220	NA
SNJ55LBC172W.A	W	CFP	16	25	506.98	26.16	6220	NA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



NOTES:

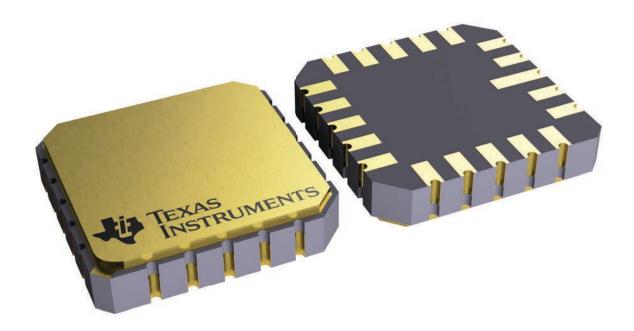
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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